



Product/Process Change Notice - PCN 14_0021 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Addition of Amkor Philippines as an Alternate Assembly Site for TSOT Packages

Publication Date: 13-Feb-2014

Effectivity Date: 14-May-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

TSOT packages are currently assembled at Carsem, Malaysia.

ADI has qualified and will be utilizing Amkor, Philippines, as an alternate assembly supplier for products in TSOT Packages.

ADI has qualified Amkor's standard assembly bill of materials, see attached BOM for details.

Reason For Change

The addition of Amkor, Philippines as an ADI assembly site of TSOT Packages will ensure continued source of supply, optimize on-time delivery, and is aligned with ADI Worldwide Manufacturing strategic plans.

ADI assembly suppliers manufacture ADI products using Analog Devices specified assembly process flows, materials, process controls and monitors. This assures that ADI customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The device fit, form, function, and reliability, as specified by Product Data Sheets, will be unaffected by this change.

Addition of Amkor Philippines as alternate assembly supplier allows future shipments of TSOT Packages from either Carsem Malaysia or Amkor Philippines assembly site.

Product Identification *(this section will describe how to identify the changed material)*

Amkor, Philippines has a Matte mold surface finish versus Carsem, Malaysia Smooth mold surface finish.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_14_0021_Rev_-_Material Set Change.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (12)**

ADR360 / ADR360AUJZ-REEL7	ADR360 / ADR360BUJZ-REEL7	ADR361 / ADR361AUJZ-REEL7	ADR361 / ADR361BUJZ-REEL7	ADR363 / ADR363AUJZ-REEL7
ADR363 / ADR363BUJZ-REEL7	ADR364 / ADR364AUJZ-REEL7	ADR364 / ADR364BUJZ-REEL7	ADR365 / ADR365AUJZ-REEL7	ADR365 / ADR365BUJZ-REEL7
ADR366 / ADR366AUJZ-REEL7	ADR366 / ADR366BUJZ-REEL7			

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	13-Feb-2014	14-May-2014	Initial Release

Analog Devices, Inc.

DocId:2738 Parent DocId:2730 Layout Rev:7